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NTC thermistors for temperature measurement

SMD NTC thermistors,
EIA case size 0603 (1608), automotive series

Series/Type: B573**V5
Date: January 2018

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SMD

Applications

- Temperature measurement and compensation

Features

- Qualification based on AEC-Q200 Rev-D
- Multilayer SMD NTC with inner electrodes
- Nickel barrier termination
- For temperature measurement up to 150 °C
- Excellent long-term aging stability in high temperature and high humidity environment
- High mechanical robustness
- Short response time
- 100% Pb free
- UL approval (E69802)

Options

- Alternative resistance ratings, resistance tolerances and B value tolerances available on request.

Delivery mode

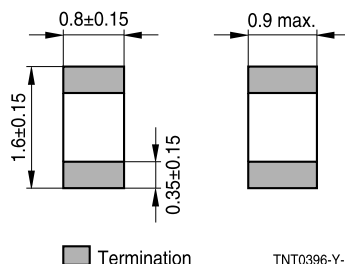
Cardboard tape, 180-mm reel

General technical data

Operating temperature range		T_{op}	-40 ... 150	°C
Max. power	(at 25 °C, on PCB)	$P_{25}^{1)}$	180	mW
Resistance tolerance		$\Delta R_R / R_R$	$\pm 1, \pm 3, \pm 5$	%
Rated temperature		T_R	25	°C
Dissipation factor	(on PCB)	$\delta_{th}^{1)}$	approx. 3	mW/K
Thermal cooling time constant	(on PCB)	$\tau_c^{1)}$	approx. 4	s
Heat capacity		$C_{th}^{1)}$	approx. 12	mJ/K

1) Depends on mounting situation

Dimensional drawing



Dimensions in mm
Approx. weight 6 mg

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Electrical specification and ordering codes

R_{25} Ω	$\Delta R_R/R_R$ %	No. of R/T characteristic	$B_{25/50}$ K	$B_{25/85}$ K	$B_{25/100}$ K	Ordering code
10 k	$\pm 1, \pm 3, \pm 5$	8509	3380	3435	$3455 \pm 1\%$	B57332V5103+360
10 k	$\pm 1, \pm 3, \pm 5$	8553	3568	3610	$3624 \pm 1\%$	B57343V5103+360
10 k	$\pm 3, \pm 5$	8500	3590	3635	$3650 \pm 3\%$	B57342V5103+060
10 k	$\pm 3, \pm 5$	8502	3940	3980	$4000 \pm 3\%$	B57351V5103+060
10 k	$\pm 3, \pm 5$	8507	4386	4455	$4480 \pm 3\%$	B57352V5103+060
22 k	$\pm 3, \pm 5$	8502	3940	3980	$4000 \pm 3\%$	B57351V5223+060
22 k	$\pm 3, \pm 5$	8507	4386	4455	$4480 \pm 3\%$	B57352V5223+060
47 k	$\pm 1, \pm 3, \pm 5$	8551	4050	4108	$4131 \pm 1.5\%$	B57356V5473+260
47 k	$\pm 3, \pm 5$	8551	4050	4108	$4131 \pm 2\%$	B57356V5473+160
47 k	$\pm 3, \pm 5$	8507	4386	4455	$4480 \pm 3\%$	B57352V5473+060
100 k	$\pm 1, \pm 3, \pm 5$	8512	4200	4260	$4282 \pm 1\%$	B57355V5104+360
100 k	$\pm 3, \pm 5$	8552	4250	4311	$4334 \pm 2\%$	B57354V5104+160
100 k	$\pm 1, \pm 3, \pm 5$	8507	4386	4455	$4480 \pm 1\%$	B57352V5104+360
100 k	$\pm 3, \pm 5$	8507	4386	4455	$4480 \pm 3\%$	B57352V5104+060

+ = Resistance tolerance

F = $\pm 1\%$

H = $\pm 3\%$

J = $\pm 5\%$

SMD
Reliability data

Tests of SMD NTC thermistors are based on AEC-Q200 Rev-D. The parts are mounted on standardized PCB.

Test	Standard	Test conditions	$\Delta R_{25}/R_{25}$ (typical) / Remarks
Pre- and post-stress electrical test		Resistance at: 25 °C and 100 °C	
High temperature exposure (storage)	MIL-STD-202, method 108	Test temperature: 150 °C Duration: 1000 h Unpowered	< 5%
		Except B57332V5103+360 B57355V5104+360 B57356V5473+260	< 1% < 2% < 1%
Temperature cycling	JESD22, method JA-104	Lower test temperature: -40 °C Upper test temperature: 150 °C Number of cycles: 1000 Transfer time: < 10 s Dwell time: 15 min Air – Air	< 5%
Biased humidity	MIL-STD-202, method 103	Test temperature: 85 °C Rel. humidity of air: 85% Duration: 1000 h Test voltage: $V_{NTC} = 0.3 \text{ V DC}$	< 5%
Operational life	MIL-STD-202, method 108	Test temperature: 150 °C $P_{max} = 0.35 \text{ mW}$ Duration: 1000 h	< 5%
External visual	MIL-STD-883E, method 2009	Visual inspection	
Physical dimensions	JESD22, method JB-100	Measured with calipers	Within the specified values
Resistance to solvents	MIL-STD-202, method 215	Not applicable for SMD thermistors (component has no marking, color coding or coating)	
Mechanical shock	MIL-STD-202, method 213	Peak value: 1500 g Half sine Condition F	< 5%

Temperature measurement and compensation	B573**V5
SMD NTC thermistors, case size 0603 (1608)	Automotive series

SMD

Test	Standard	Test conditions	$\Delta R_{25}/R_{25}$ (typical) / Remarks
Vibration	MIL-STD-202, method 204	Acceleration: 5 g Sweep time: 20 min Frequency range: 10 ... 2000 Hz 3 × 12 cycles	< 1%
Resistance to soldering heat	MIL-STD-202, method 210	Dip: 260 °C; 10 s 1 heat cycle	< 3%
		Except B57332V5103+360 B57355V5104+360 B57356V5473+260	< 1% < 1% < 1%
ESD	AEC-Q200-002, method -002	Discharge capacitance: 150 pF Discharge resistance: 2 kΩ Charging voltage: 6 kV Contact discharge 2 pulses in each polarity	< 5%
Solderability	J-STD-002	a) Dip: 235 °C; 5 s: aging 4 h @ 155 °C b) Dip: 215 °C; 5 s: steam aging 8 h @ 92 °C c) Dip: 260 °C; 7 s: steam aging 8 h @ 92 °C	95% of termination wetted
Electrical characterization		R(25 °C), R(100 °C), B(25/100)	Within the specified values
Flammability	UL-94, V-0 or V-1	Not applicable for SMD thermistors (component is not coated or encapsulated with plastic materials)	
Board flex	AEC-Q200-005, method -005	Max. bending: 1 mm Duration @ max. bending: 60 s	< 2%
Terminal strength	AEC-Q200-006, method -006	Max. F: 5 N	< 2%
Resistance drift after soldering		Reflow soldering profile Wave soldering profile	< 1%

SMD
R/T characteristics

R/T No.	8500		8502		8507	
T (°C)	B _{25/100} = 3650 K		B _{25/100} = 4000 K		B _{25/100} = 4480 K	
	R _T /R ₂₅	α (%/K)	R _T /R ₂₅	α (%/K)	R _T /R ₂₅	α (%/K)
-55.0	63.917	6.8	96.158	7.4	142.71	7.9
-50.0	45.889	6.5	66.892	7.1	96.913	7.6
-45.0	33.344	6.3	47.127	6.9	66.637	7.4
-40.0	24.504	6.1	33.606	6.6	46.366	7.1
-35.0	18.201	5.8	24.243	6.4	32.629	6.9
-30.0	13.657	5.6	17.681	6.2	23.213	6.7
-25.0	10.347	5.5	13.032	6.0	16.686	6.5
-20.0	7.9114	5.3	9.702	5.8	12.115	6.3
-15.0	6.1019	5.1	7.2923	5.6	8.8803	6.1
-10.0	4.7454	4.9	5.5314	5.4	6.5692	5.9
-5.0	3.7198	4.8	4.2325	5.3	4.9025	5.8
0.0	2.938	4.6	3.2657	5.1	3.6896	5.6
5.0	2.3372	4.5	2.54	4.9	2.7994	5.4
10.0	1.8722	4.4	1.9907	4.8	2.1406	5.3
15.0	1.5096	4.2	1.5716	4.7	1.6492	5.1
20.0	1.2249	4.1	1.2494	4.5	1.2798	5.0
25.0	1.0000	4.0	1.0000	4.4	1.0000	4.9
30.0	0.82111	3.9	0.80552	4.3	0.78663	4.7
35.0	0.67798	3.8	0.65288	4.1	0.62277	4.6
40.0	0.56279	3.7	0.53229	4.0	0.4961	4.5
45.0	0.46958	3.6	0.43645	3.9	0.39757	4.4
50.0	0.39374	3.5	0.35981	3.8	0.32044	4.3
55.0	0.33171	3.4	0.29819	3.7	0.2597	4.1
60.0	0.28073	3.3	0.24837	3.6	0.21161	4.0
65.0	0.23863	3.2	0.20787	3.5	0.17331	3.9
70.0	0.2037	3.1	0.17479	3.4	0.14265	3.8
75.0	0.17459	3.0	0.14763	3.3	0.11799	3.8
80.0	0.15022	3.0	0.12523	3.2	0.098035	3.7
85.0	0.12975	2.9	0.10667	3.2	0.081823	3.6
90.0	0.11247	2.8	0.091227	3.1	0.068589	3.5
95.0	0.097838	2.8	0.078319	3.0	0.057735	3.4
100.0	0.085396	2.7	0.067488	2.9	0.048796	3.3
105.0	0.074781	2.6	0.058363	2.9	0.041403	3.2
110.0	0.065691	2.6	0.050647	2.8	0.035263	3.2
115.0	0.057883	2.5	0.044098	2.7	0.030143	3.1
120.0	0.051153	2.4	0.03852	2.7	0.025858	3.0
125.0	0.045335	2.4	0.033752	2.6	0.022258	3.0
130.0	0.040289	2.3	0.029663	2.6	0.019223	2.9
135.0	0.0359	2.3	0.026146	2.5	0.016655	2.8
140.0	0.032071	2.2	0.023111	2.4	0.014476	2.8
145.0	0.028723	2.2	0.020484	2.4	0.012619	2.7
150.0	0.025786	2.1	0.018203	2.3	0.011033	2.7

SMD
R/T characteristics

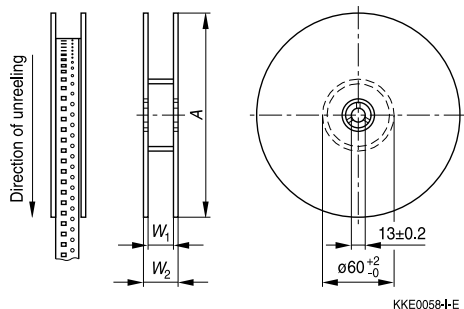
R/T No.	8509		8512		8551	
T (°C)	B _{25/100} = 3455 K		B _{25/100} = 4282 K		B _{25/100} = 4131 K	
	R _T /R ₂₅	α (%/K)	R _T /R ₂₅	α (%/K)	R _T /R ₂₅	α (%/K)
-55.0	44.605	5.9	130.38	8.0	111.73	7.8
-50.0	33.281	5.8	88.097	7.7	76.28	7.5
-45.0	25.044	5.6	60.444	7.4	52.88	7.2
-40.0	19.003	5.4	42.065	7.1	37.187	6.9
-35.0	14.536	5.3	29.666	6.9	26.498	6.7
-30.0	11.206	5.1	21.185	6.6	19.117	6.4
-25.0	8.7041	5.0	15.307	6.4	13.954	6.2
-20.0	6.8104	4.8	11.183	6.2	10.297	6.0
-15.0	5.3665	4.7	8.2558	6.0	7.677	5.8
-10.0	4.2576	4.6	6.1553	5.8	5.780	5.6
-5.0	3.4001	4.4	4.6324	5.6	4.3916	5.4
0.0	2.7326	4.3	3.5175	5.4	3.3661	5.2
5.0	2.2096	4.2	2.6935	5.3	2.6014	5.1
10.0	1.7973	4.1	2.0792	5.1	2.0262	4.9
15.0	1.4703	4.0	1.6173	4.9	1.5901	4.8
20.0	1.2093	3.9	1.2673	4.8	1.2567	4.6
25.0	1.0000	3.7	1.0000	4.7	1.0000	4.5
30.0	0.83113	3.6	0.79435	4.5	0.8009	4.4
35.0	0.69418	3.6	0.63504	4.4	0.6454	4.3
40.0	0.58255	3.5	0.51079	4.3	0.5232	4.1
45.0	0.49112	3.4	0.41327	4.2	0.42650	4.0
50.0	0.41587	3.3	0.33625	4.1	0.34959	3.9
55.0	0.35365	3.2	0.27507	4.0	0.28804	3.8
60.0	0.30197	3.1	0.22618	3.9	0.23851	3.7
65.0	0.25888	3.0	0.18692	3.8	0.19844	3.6
70.0	0.22278	3.0	0.15521	3.7	0.16587	3.5
75.0	0.19243	2.9	0.12948	3.6	0.13926	3.5
80.0	0.16681	2.8	0.10850	3.5	0.11742	3.4
85.0	0.1451	2.8	0.091301	3.4	0.09941	3.3
90.0	0.12663	2.7	0.077149	3.3	0.08449	3.2
95.0	0.11088	2.6	0.065451	3.2	0.07209	3.1
100.0	0.097381	2.6	0.055740	3.2	0.06174	3.1
105.0	0.085788	2.5	0.047647	3.1	0.05305	3.0
110.0	0.075795	2.4	0.040874	3.0	0.04575	2.9
115.0	0.067155	2.4	0.035186	3.0	0.039583	2.9
120.0	0.059663	2.3	0.030391	2.9	0.034356	2.8
125.0	0.053146	2.3	0.026334	2.8	0.029912	2.7
130.0	0.047463	2.2	0.022890	2.8	0.026120	2.7
135.0	0.042493	2.2	0.019957	2.7	0.022875	2.6
140.0	0.038134	2.1	0.017451	2.7	0.020089	2.6
145.0	0.034302	2.1	0.015303	2.6	0.017690	2.5
150.0	0.030925	2.1	0.013456	2.5	0.015619	2.5

SMD
R/T characteristics

R/T No.	8552		8553	
T (°C)	B _{25/100} = 4334 K		B _{25/100} = 3624 K	
	R _T /R ₂₅	α (%/K)	R _T /R ₂₅	α (%/K)
-55.0	138.15	8.1	63.618	6.8
-50.0	92.920	7.8	45.642	6.5
-45.0	63.468	7.5	33.144	6.3
-40.0	43.979	7.2	24.345	6.1
-35.0	30.888	6.9	18.077	5.8
-30.0	21.969	6.7	13.562	5.6
-25.0	15.812	6.5	10.275	5.5
-20.0	11.509	6.2	7.8576	5.3
-15.0	8.4659	6.0	6.0623	5.1
-10.0	6.2899	5.8	4.7168	4.9
-5.0	4.7178	5.7	3.6995	4.8
0.0	3.5705	5.5	2.9240	4.6
5.0	2.7255	5.3	2.3280	4.5
10.0	2.0974	5.2	1.8664	4.4
15.0	1.6266	5.0	1.5064	4.2
20.0	1.2709	4.9	1.2236	4.1
25.0	1.0000	4.7	1	4.0
30.0	0.79218	4.6	0.82203	3.9
35.0	0.63161	4.5	0.67952	3.8
40.0	0.50672	4.3	0.56473	3.6
45.0	0.40894	4.2	0.47175	3.5
50.0	0.33191	4.1	0.39603	3.5
55.0	0.27087	4.0	0.33404	3.4
60.0	0.22222	3.9	0.28303	3.3
65.0	0.18322	3.8	0.24086	3.2
70.0	0.15181	3.7	0.20584	3.1
75.0	0.12637	3.6	0.17662	3.0
80.0	0.10566	3.5	0.15214	2.9
85.0	0.088735	3.4	0.13154	2.9
90.0	0.074831	3.4	0.11414	2.8
95.0	0.063360	3.3	0.099391	2.7
100.0	0.053856	3.2	0.086835	2.7
105.0	0.045950	3.1	0.076111	2.6
110.0	0.039346	3.1	0.066919	2.5
115.0	0.033810	3.0	0.059014	2.5
120.0	0.029151	2.9	0.052194	2.4
125.0	0.025217	2.9	0.046292	2.4
130.0	0.021882	2.8	0.041168	2.3
135.0	0.019047	2.7	0.036708	2.3
140.0	0.016628	2.7	0.032814	2.2
145.0	0.014559	2.6	0.029405	2.2
150.0	0.012782	2.6	0.026412	2.1

SMD
Taping and packing
1 Taping of SMD NTC thermistors

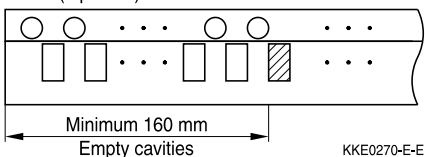
Tape and reel packing according to IEC 60286-3.
Tape material: Cardboard or blister, tape width 8 ± 0.30 mm

2 Reel packing

Dimensions in mm

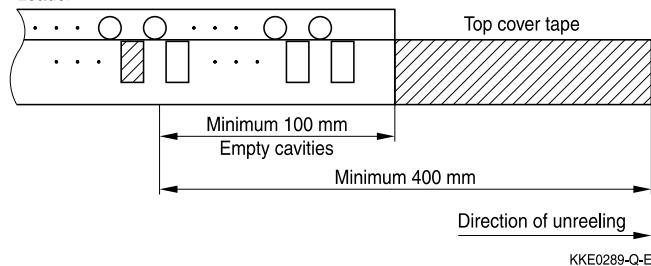
	8-mm tape	
	180-mm reel	330-mm reel
A	180 +0/-3	330 +0/-2.0
W ₁	8.4 +1.5/-0	8.4 +1.5/-0
W ₂	14.4 max.	14.4 max.

Leader, trailer

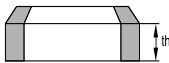
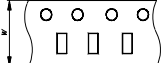


Trailer (tape end)



Leader



SMD
Packing units for discrete chip

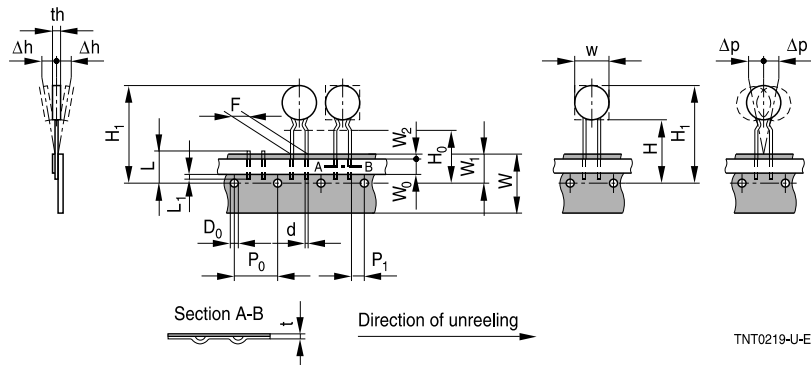
					
Case size	Chip thickness	Cardboard tape	Blister tape	∅ 180-mm reel	∅ 330-mm reel
inch/mm	th	W	W	pcs.	pcs.
0402/1005	0.5 mm	8 mm	–	10000	50000
0603/1608	0.8 mm	8 mm	8 mm	4000	16000
0805/2012	0.8 mm	–	8 mm	2000/ 4000	16000
	1.2 mm	–	8 mm		
1206/3216	0.8 mm	–	8 mm	2000	12000
	1.2 mm	–	8 mm		

3 Packing codes

The last two digits of the complete ordering code state the packing mode:

Last two digits			
60	SMD	Cardboard tape	180-mm reel packing
62	SMD	Blister tape	180-mm reel packing
70	SMD	Cardboard tape	330-mm reel packing
72	SMD	Blister tape	330-mm reel packing

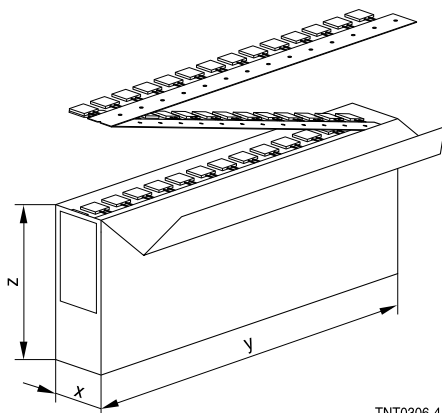
SMD
4 Taping of radial leaded NTC thermistors
Dimensions and tolerances

 Lead spacing $F = 2.5 \text{ mm}$ and 5.0 mm (taping to IEC 60286-2)

Dimensions (mm)

	Lead spacing 2.5 mm	Lead spacing 5 mm	Tolerance of lead spacing 2.5/5 mm	Remarks
w	11.0	11.5	max.	
th	5.0	6.0	max.	
d	0.5/0.6	0.5/0.6	± 0.05	
P ₀	12.7	12.7	± 0.3	$\pm 1 \text{ mm}$ / 20 sprocket holes
P ₁	5.1	3.85	± 0.7	
F	2.5	5.0	$+0.6/-0.1$	
Δh	0	0	± 2.0	measured at top of component body
Δp	0	0	± 1.3	
W	18.0	18.0	± 0.5	
W ₀	5.5	5.5	min.	peel-off force $\geq 5 \text{ N}$
W ₁	9.0	9.0	$+0.75/-0.5$	
W ₂	3.0	3.0	max.	
H	18.0	18.0	$+2.0/-0$	
H ₀	16.0	16.0	± 0.5	
H ₁	32.2	32.2	max.	
D ₀	4.0	4.0	± 0.2	
t	0.9	0.9	max.	without wires
L	11.0	11.0	max.	
L ₁	4.0	4.0	max.	

SMD
Types of packing

Ammo packing

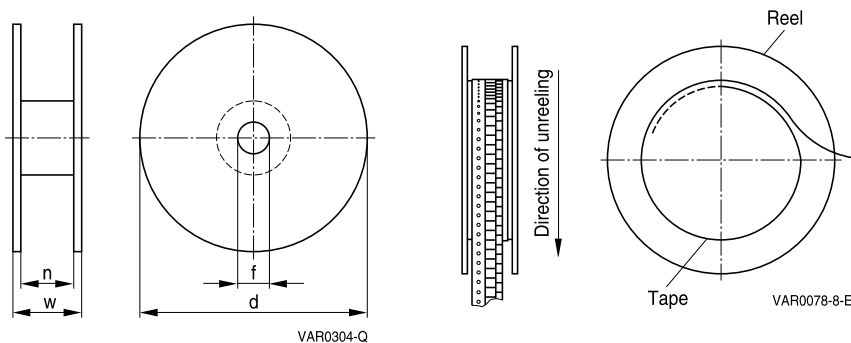


TNT0306-4

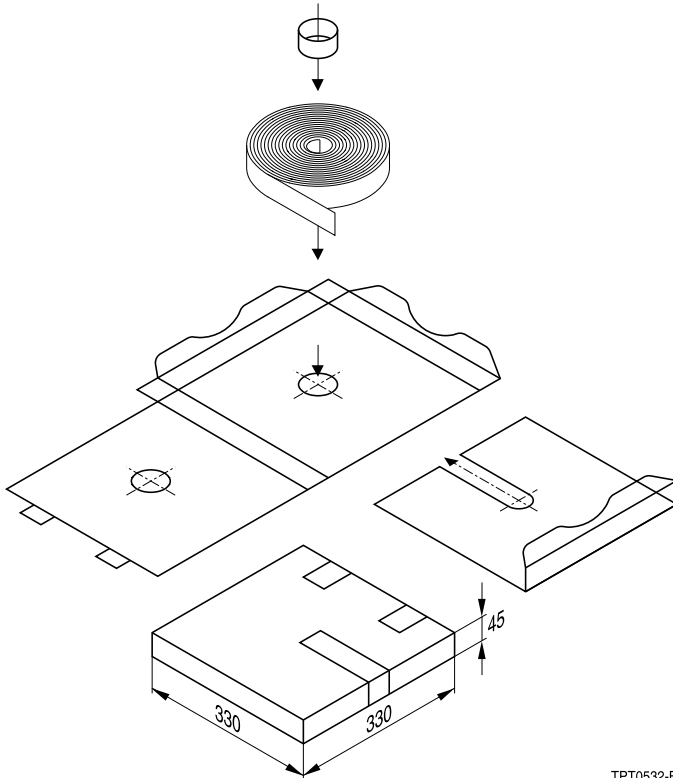
Ammo type	x	y	z
I	80	240	210

Packing unit: 1000 - 2000 pcs./reel

Reel packing


Packing unit: 1000 - 2000 pcs./reel
Reel dimensions (in mm)

Reel type	d	f	n	w
I	360 max.	31 ±1	approx. 45	54 max.

SMD
Cassette packing


TPT0532-B

Packing unit: 1000 - 2000 pcs./cassette

Bulk packing

The components are packed in cardboard boxes, the size of which depends on the order quantity.

SMD
5 Packing codes

The last two digits of the complete ordering code state the packing mode:

Last two digits			
00, 01, 02, 03,04, 05, 06, 07, 08	–	Bulk	–
40, 41	–	Bulk	–
45	–	Bulk	–
50	Radial leads, kinked	Cardboard tape	Cassette packing
51	Radial leads, kinked	Cardboard tape	360-mm reel packing
52	Radial leads, straight	Cardboard tape	Cassette packing
53	Radial leads, straight	Cardboard tape	360-mm reel packing
54	Radial leads, kinked	Cardboard tape	AMMO packing
55	Radial leads, straight	Cardboard tape	AMMO packing

(If no packing code is indicated, this corresponds to 40)

Example 1:	B57164K0102J000	Bulk
	B57164K0102J052	Cardboard tape, cassette packing
Example 2:	B57881S0103F002	Bulk
	B57881S0103F251	Cardboard tape, reel packing

SMD

Mounting instructions

1 Soldering

1.1 Leaded NTC thermistors

Leaded thermistors comply with the solderability requirements specified by CECC.

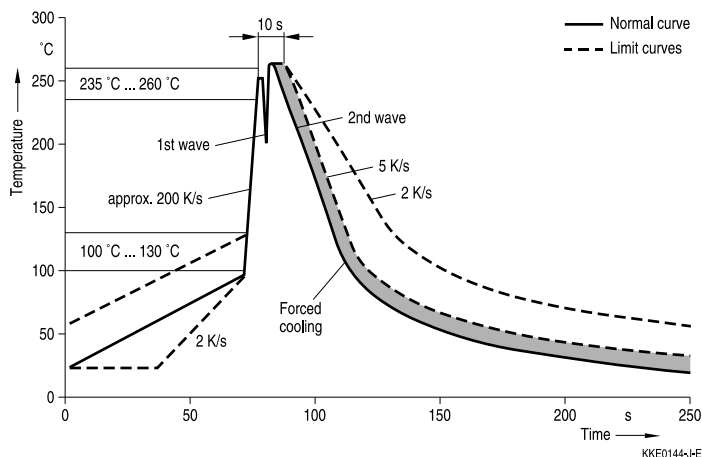
When soldering, care must be taken that the NTC thermistors are not damaged by excessive heat. The following maximum temperatures, maximum time spans and minimum distances have to be observed:

	<i>Dip soldering</i>	<i>Iron soldering</i>
Bath temperature	max. 260 °C	max. 360 °C
Soldering time	max. 4 s	max. 2 s
Distance from thermistor	min. 6 mm	min. 6 mm

Under more severe soldering conditions the resistance may change.

1.1.1 Wave soldering

Temperature characteristic at component terminal with dual wave soldering



1.2 Leadless NTC thermistors

In case of NTC thermistors without leads, soldering is restricted to devices which are provided with a solderable metallization. The temperature shock caused by the application of hot solder may produce fine cracks in the ceramic, resulting in changes in resistance.

To prevent leaching of the metallization, solder with silver additives or with a low tin content

SMD

should be used. In addition, soldering methods should be employed which permit short soldering times.

1.3 SMD NTC thermistors

SMD NTC thermistors can be provided with a nickel barrier termination or on special request with silver-palladium termination. The use of no-clean solder products is recommended. In any case mild, non-activated fluxes should be used. Flux residues after soldering should be minimized.

- SMD NTCs with AgPd termination are not approved for lead-free soldering.
- Nickel barrier termination

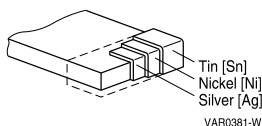


Figure 1
SMD NTC thermistors, structure of nickel barrier termination

The nickel barrier layer of the silver/nickel/tin termination (see figure 1) prevents leaching of the silver base metallization layer. This allows great flexibility in the selection of soldering parameters.

The tin prevents the nickel layer from oxidizing and thus ensures better wetting by the solder. The nickel barrier termination is tested for all commonly-used soldering methods according to IEC 60068-2-58. Insufficient preheating may cause ceramic cracks. Rapid cooling by dipping in solvent is not recommended.

The following test and process conditions apply for nickel barrier termination.

SMD
1.3.1 Solderability (test to IEC 60068-2-58)

Preconditioning: Immersion into flux F-SW 32.

 Evaluation criterion: Wetting of soldering areas $\geq 95\%$.

Solder	Bath temperature (°C)	Dwell time (s)
SnPb 60/40	215 \pm 3	3 \pm 0.3
SnAg (3.0 ... 4.0), Cu (0.5 ... 0.9)	245 \pm 3	3 \pm 0.3

1.3.2 Resistance to soldering heat (test to IEC 60068-2-58)

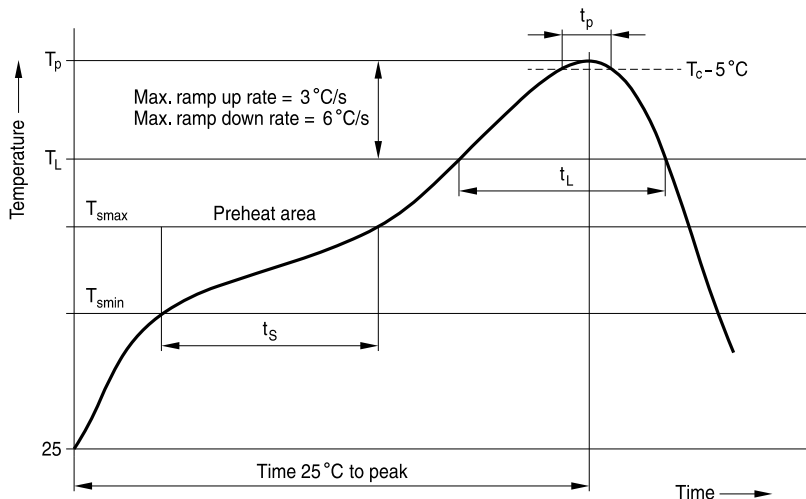
Preconditioning: Immersion into flux F-SW 32.

 Evaluation criterion: Leaching of side edges $\leq 1/3$.

Solder	Bath temperature (°C)	Dwell time (s)
SnPb 60/40	260 \pm 5	10 \pm 1
SnAg (3.0 ... 4.0), Cu (0.5 ... 0.9)	260 \pm 5	10 \pm 1

1.3.3 Reflow soldering

Temperature ranges for reflow soldering acc. to IEC 60068-2-58 recommendations.



TNT0660-P-E

SMD

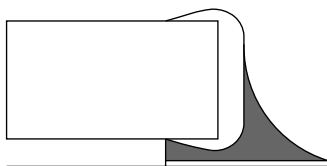
Profile feature		Sn-Pb eutectic assembly	Pb-free assembly
Preheat and soak			
- Temperature min	T_{smin}	100 °C	150 °C
- Temperature max	T_{smax}	150 °C	200 °C
- Time	t_{smin} to t_{smax}	60 ... 120 s	60 ... 120 s
Average ramp-up rate	T_{smax} to T_p	3 °C/ s max.	3 °C/ s max.
Liquidous temperature	T_L	183 °C	217 °C
Time at liquidous	t_L	40 ... 150 s	40 ... 150 s
Peak package body temperature	T_p	215 °C ... 260 °C ¹⁾	235 °C ... 260 °C
Time above ($T_p - 5$ °C)	t_p	10 ... 40 s	10 ... 40 s
Average ramp-down rate	T_p to T_{smax}	6 °C/ s max.	6 °C/ s max.
Time 25 °C to peak temperature		max. 8 minutes	max. 8 minutes

1) Depending on package thickness.

Notes: All temperatures refer to topside of the package, measured on the package body surface.

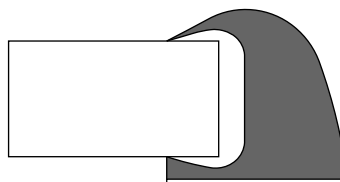
Number of reflow cycles: 3

Iron soldering should be avoided, hot air methods are recommended for repair purposes.

Solder joint profiles for silver/nickel/tin terminations


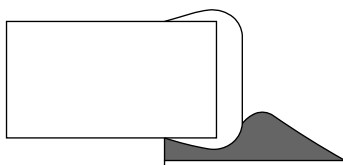
Good solder joint

TNT0565-G-E



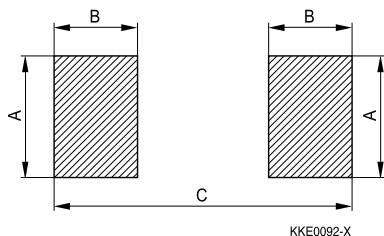
Too much solder
Pad geometry too large

KKE0071-A-E



Poor wetting

KKE0072-I-E

SMD
1.3.4 Recommended geometry of solder pads


Recommended maximum dimensions (mm)

Case size inch/mm	A	B	C
0402/1005	0.6	0.6	1.7
0603/1608	1.0	1.0	3.0
0805/2012	1.3	1.2	3.4
1206/3216	1.8	1.2	4.5

2 Conductive adhesion

An alternative to soldering for silver-palladium terminated components is the gluing of thermistors with conductive adhesives. The benefit of this method is that it involves no thermal stress. The adhesives used must be chemically inert.

3 Clamp contacting

Pressure contacting by means of clamps is particularly suitable for applications involving frequent switching and high turn-on powers.

4 Robustness of terminations (leaded types)

The leads meet the requirements of IEC 60068-2-21. They may not be bent closer than 4 mm from the solder joint on the thermistor body or from the point at which they leave the feed-throughs. During bending, any mechanical stress at the outlet of the leads must be removed. The bending radius should be at least 0.75 mm.

SMD

Tensile strength: Test Ua1:

Value of applied force for Ua1 test:

Diameter (d) of corresponding round leads	Force with tolerance of $\pm 10\%$
$\varnothing \leq 0.25$ mm	1.0 N
$0.25 < \varnothing \leq 0.35$ mm	2.5 N
$0.35 < \varnothing \leq 0.50$ mm	5.0 N
$0.50 < \varnothing \leq 0.80$ mm	10.0 N

Bending strength: Test Ub:

Two 90°-bends in opposite directions

Value of applied force for Ub test:

Diameter (d) of corresponding round leads	Force with tolerance of $\pm 10\%$
$\varnothing \leq 0.25$ mm	0.5 N
$0.25 < \varnothing \leq 0.35$ mm	1.25 N
$0.35 < \varnothing \leq 0.50$ mm	2.5 N
$0.50 < \varnothing \leq 0.80$ mm	5 N

Torsional strength: Test Uc: severity 2

The lead is bent by 90° at a distance of 6 to 6.5 mm from the thermistor body.

The bending radius of the leads should be approx. 0.75 mm. Two torsions of 180° each (severity 2).

When subjecting leads to mechanical stress, the following should be observed:

Tensile stress on leads

During mounting and operation tensile forces on the leads are to be avoided.

Bending of leads

Bending of the leads directly on the thermistor body is not permissible.

A lead may be bent at a minimum distance of twice the wire's diameter +4 mm from the solder joint on the thermistor body. During bending the wire must be mechanically relieved at its outlet. The bending radius should be at least 0.75 mm.

SMD

5 Sealing and potting

Sealing or potting processes can affect the reliability of the component.

When thermistors are sealed, potted or overmolded, there must be no mechanical stress caused by thermal expansion during the production process (curing / overmolding process) and during later operation. The upper category temperature of the thermistor must not be exceeded. Ensure that the materials used (sealing / potting compound and plastic material) are chemically neutral. As thermistors are temperature sensitive components it should be considered that molding can affect the thermal surrounding and may influence e.g. the response time.

Extensive testing is encouraged in order to determine whether overmolding or potting influences the functionality and/ or reliability of the component.

6 Cleaning

Cleaning processes can affect the reliability of the component.

If cleaning is necessary, mild cleaning agents are recommended. Cleaning agents based on water are not allowed. Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks which might lead to reduced reliability and/ or lifetime.

7 Storage

In order to maintain their solderability, thermistors must be stored in a non-corrosive atmosphere. Humidity, temperature and container materials are critical factors.

Do not store SMDs where they are exposed to heat or direct sunlight. Otherwise, the packing material may be deformed or SMDs may stick together, causing problems during mounting. After opening the factory seals, such as polyvinyl-sealed packages, use the SMDs as soon as possible.

The components should be left in the original packing. Touching the metallization of unsoldered thermistors may change their soldering properties.

Storage temperature: –25 °C up to 45 °C

Relative humidity (without condensation): ≤75% annual mean

<95%, maximum 30 days per annum

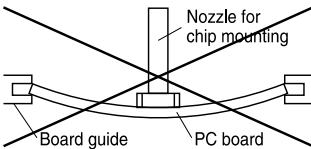
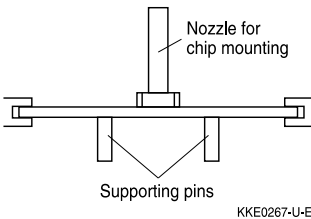
Solder the thermistors listed in this data book after shipment from EPCOS within the time specified:

SMDs with AgPd termination: 6 months

SMDs with nickel barrier termination: 12 months

Leadless components: 12 months

Leaded components: 24 months

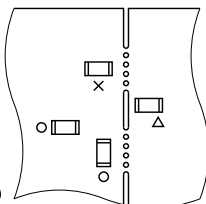
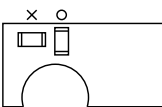
SMD
8 Placement and orientation of SMD NTC thermistors on PCB
a) Component placement
Incorrect

Correct


It is recommended that the PC board should be held by means of some adequate supporting pins such as shown left to prevent the SMDs from being damaged or cracked.

b) Cracks

SMDs located near an easily warped area

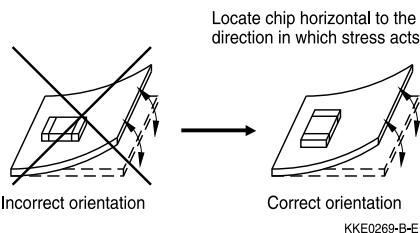
SMD breakage probability due to stress at a breakaway



O = correct
 X = incorrect
 Δ = incorrect
 (under certain conditions)

KKE0268-3-E

When placing a component near an area which is apt to bend or a grid groove on the PC board, it is advisable to have both electrodes subjected to uniform stress, or to position the component's electrodes at right angles to the grid groove or bending line (see c) Component orientation).

c) Component orientation


Choose a mounting position that minimizes the stress imposed on the chip during flexing or bending of the board.

SMD

Cautions and warnings

General

See "Important notes" on page 2.

Storage

- Store thermistors only in original packaging. Do not open the package prior to processing.
- Storage conditions in original packaging: storage temperature $-25\text{ }^{\circ}\text{C} \dots +45\text{ }^{\circ}\text{C}$, relative humidity $\leq 75\%$ annual mean, $< 95\%$ maximum 30 days per annum, dew precipitation is inadmissible.
- Do not store thermistors where they are exposed to heat or direct sunlight. Otherwise, the packing material may be deformed or components may stick together, causing problems during mounting.
- Avoid contamination of thermistor surface during storage, handling and processing.
- Avoid storage of thermistors in harmful environments like corrosive gases (SO_x , Cl etc).
- Use the components as soon as possible after opening the original packaging.
- Solder thermistors within the time specified after shipment from EPCOS.
For leaded components this is 24 months, for SMD components with nickel barrier termination 12 months, for leadless components this is 12 months, for SMD components with AgPd termination 6 months.

Handling

- NTC thermistors must not be dropped. Chip-offs or any other damage must not be caused during handling of NTCs.
- Do not touch components with bare hands. Gloves are recommended.
- Avoid contamination of thermistor surface during handling.
- Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.

Bending / twisting leads

- A lead (wire) may be bent at a minimum distance of twice the wire's diameter plus 4 mm from the component head or housing. When bending ensure the wire is mechanically relieved at the component head or housing. The bending radius should be at least 0.75 mm.

Soldering

- Use resin-type flux or non-activated flux.
- Insufficient preheating may cause ceramic cracks.
- Rapid cooling by dipping in solvent is not recommended.
- Complete removal of flux is recommended.

SMD**Mounting**

- Ensure that no thermo-mechanical stress occurs due to production processes (curing or overmolding processes) when thermistors are sealed, potted or overmolded or during their subsequent operation. The maximum temperature of the thermistor must not be exceeded. Ensure that the materials used (sealing/potting compound and plastic material) are chemically neutral.
- Electrodes/contacts must not be scratched or damaged before/during/after the mounting process.
- Contacts and housing used for assembly with the thermistor must be clean before mounting.
- Ensure that adjacent materials are designed for operation at temperatures comparable to the surface temperature of the thermistor. Be sure that surrounding parts and materials can withstand the temperature.
- Avoid contamination of the thermistor surface during processing.
- The connections of sensors (e.g. cable end, wire end, plug terminal) may only be exposed to an environment with normal atmospheric conditions.
- Tensile forces on cables or leads must be avoided during mounting and operation.
- Bending or twisting of cables or leads directly on the thermistor body is not permissible.
- Avoid using chemical substances as mounting aids. It must be ensured that no water or other liquids enter the NTC thermistors (e.g. through plug terminals). In particular, water based substances (e.g. soap suds) must not be used as mounting aids for sensors.
- The use of no-clean solder products is recommended. In any case mild, non-activated fluxes should be used. Flux residues after soldering should be minimized.

Operation

- Use thermistors only within the specified operating temperature range.
- Use thermistors only within the specified power range.
- Environmental conditions must not harm the thermistors. Only use the thermistors under normal atmospheric conditions or within the specified conditions.
- Contact of NTC thermistors with any liquids and solvents shall be prevented. It must be ensured that no water enters the NTC thermistors (e.g. through plug terminals). For measurement purposes (checking the specified resistance vs. temperature), the component must not be immersed in water but in suitable liquids (e.g. perfluoropolyethers such as Galden).
- Avoid dewing and condensation unless thermistor is specified for these conditions.
- Bending or twisting of cables and/or wires is not permissible during operation of the sensor in the application.
- Be sure to provide an appropriate fail-safe function to prevent secondary product damage caused by malfunction.

This listing does not claim to be complete, but merely reflects the experience of EPCOS AG.

Display of ordering codes for EPCOS products

The ordering code for one and the same EPCOS product can be represented differently in data

SMD

sheets, data books, other publications, on the EPCOS website, or in order-related documents such as shipping notes, order confirmations and product labels. **The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products.** Detailed information can be found on the Internet under www.epcos.com/orderingcodes